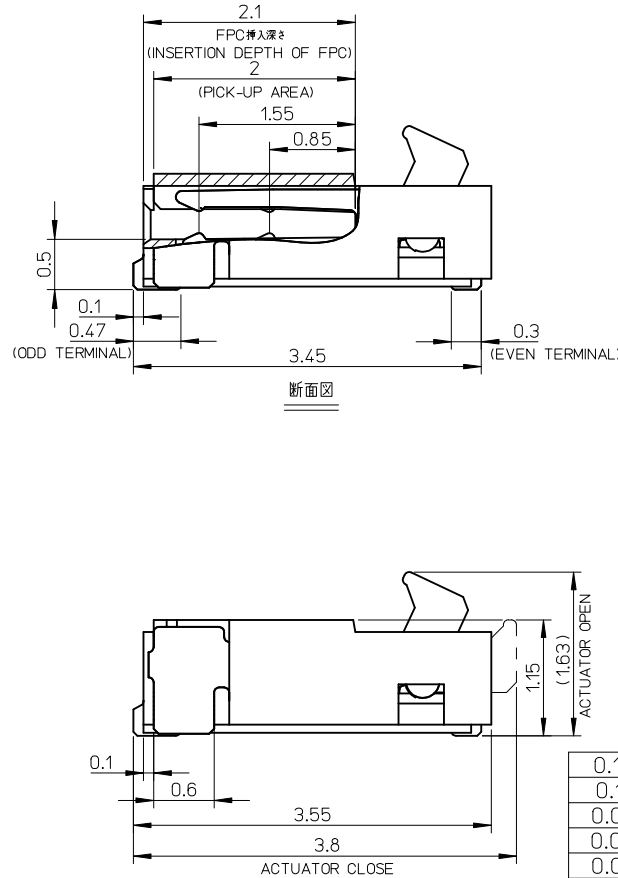
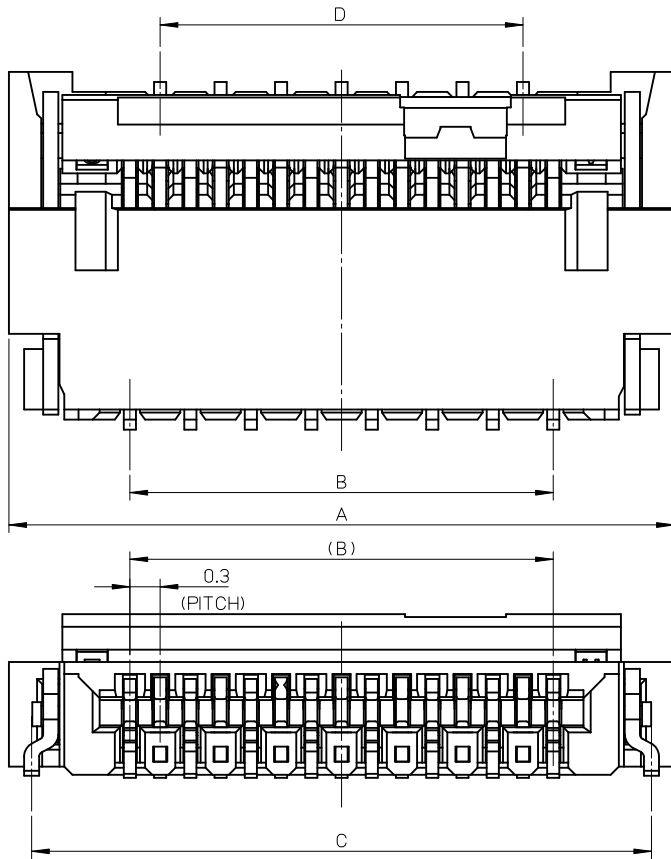




注記 NOTES:

1.材質 MATERIAL

ハウジング: LCP(液晶ポリマー)、白色、ガラス充填、UL94V-0
HOUSING: LIQUID CRYSTAL POLYMER, WHITE (NATURAL)
GLASS FILLED, UL94V-0
アクチュエータ: ポリアミド樹脂
黑色、ガラス充填、UL94V-HB

ACTUATOR: POLYAMIDE

BLACK GLASS FILLED, UL94V-HB

ターミナル: 銅合金 (t=0.12)

TERMINAL: COPPER ALLOY (t=0.12)

金具: 焼青銅 (t=0.15)

NAIL: PHOSPHOR BRONZE (t=0.15)

2.めっき仕様 PLATING

ターミナル TERMINAL

接点部: 金めっき 0.1μm以上

CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM

半田付け部: 金めっき

SOLDER TAIL AREA: GOLD

下地めっき: ニッケル 1.0μm以上

UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM

金具 NAIL

銅めっき 1.0μm以上

TIN PLATING 1.0 MICROMETER MINIMUM

下地めっき: ニッケル 1.0μm以上

UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM

3.平坦度は、0.1ミリ以下とする。

TAILS COPLANARITY TO BE 0.1 MAXIMUM.

4.製品の取り扱いについては、コネクタ取り扱い説明書 (AS-502598-001) を参照願います。

PLEASE REFER TO INSTRUCTION MANUAL (AS-502598-001)
FOR 0.3 FPC CONNECTOR BACK FLIP.

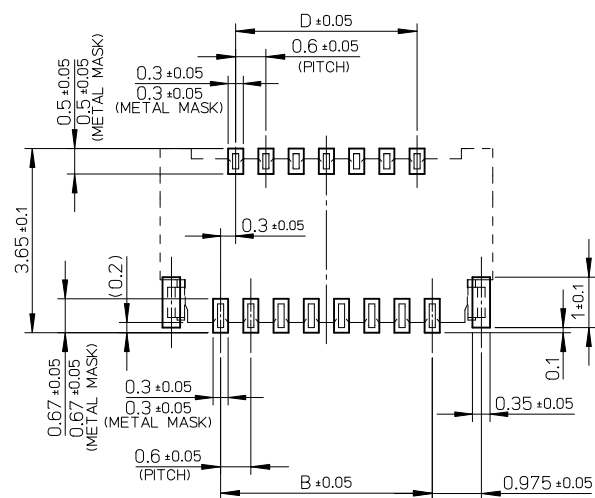
5.ELV及びRoHS適合品

ELV AND RoHS COMPLIANT

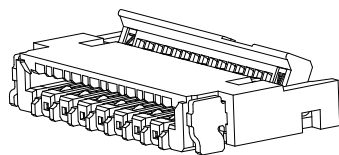
0.125	14.4	16.95	15	17.4	502598-5191	51
0.112	12.6	15.15	13.2	15.6	502598-4591	45
0.098	10.8	13.35	11.4	13.8	502598-3991	39
0.085	9	11.55	9.6	12	502598-3391	33
0.077	7.8	10.35	8.4	10.8	502598-2991	29
0.072	7.2	9.75	7.8	10.2	502598-2791	27
0.068	6.6	9.15	7.2	9.6	502598-2591	25
0.063	6	8.55	6.6	9	502598-2391	23
重さ (g) WEIGHT (g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES NO. 502598-**11

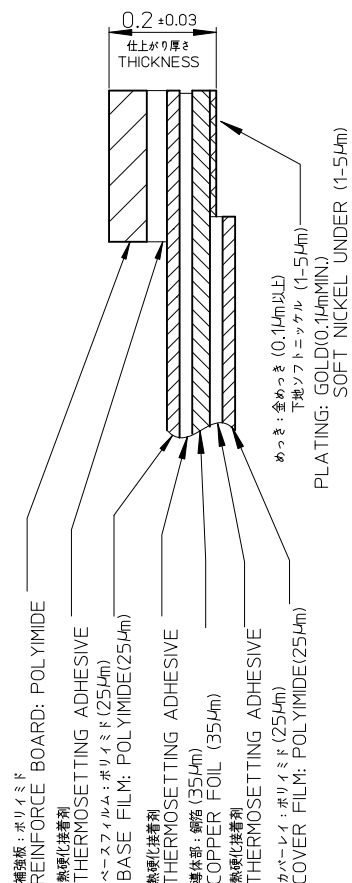
REVISED EC NO. :J2012-0121 DRWN:YUHASEGAWA 2011/07/25 CHKD:K TAKAHASHI 2011/07/25 APPR:KMORIKAWA 2011/07/28	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY HONO	DATE 2009/07/21	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY				
		10 OVER 30 UNDER	± 0.25	CHECKED BY HSHIMOYAMA	DATE 2009/07/21					
		30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2009/07/21	MOLEX INCORPORATED				
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502598-001		1 OF 2		
	REV				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



推奨基板寸法
RECOMMENDED P.W.B. PATTERN LAYOUT
推奨メタルマスク厚: $t=0.1\text{mm}$
RECOMMENDED METAL MASK THICKNESS: $t=0.1\text{mm}$

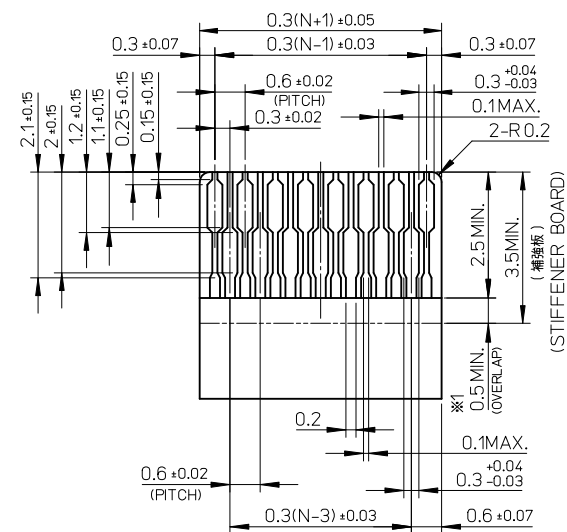


ISO VIEW (参考)



FPC構成推奨仕様

STRUCTURE OF FPC



N: 極数
N:CIRCUITS

適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

FPCについて:

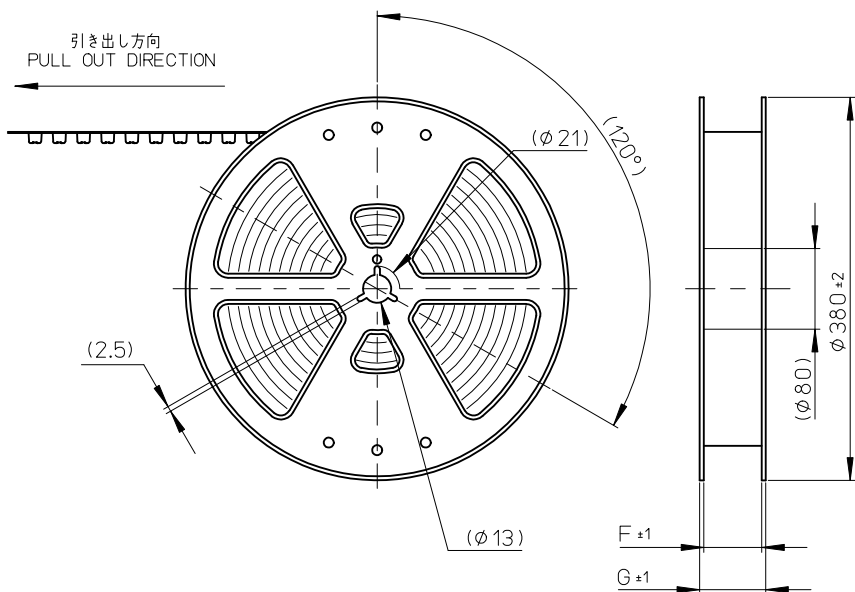
抜き方向は、導体側から補強板側を推奨致します。
 補強フィルム材質は、ポリイミドを推奨致します。
 接着剤は熱硬化性接着剤を推奨致します。
 尚、接着剤の接点部への付着は導通不良の原因になりますので、
 染み出しが無い様、お願い致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE
ADHERING BECAUSE THERE IS A POSSIBILITY THAT
THE EXTRA ADHESIVE CAUSES THE DEFECT IN
ELECTRICAL CONTINUITY.

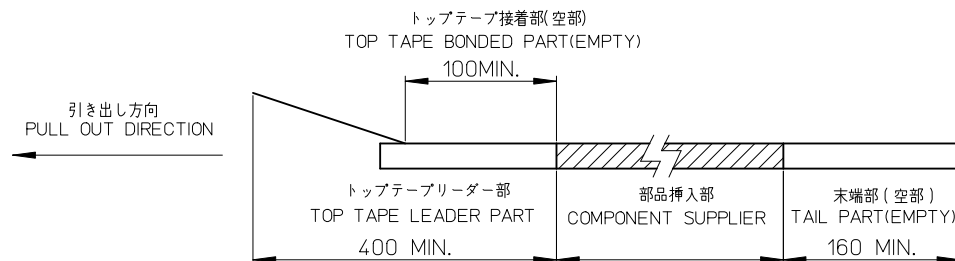
※1 補強板の長さが図面通りに確保できない場合は、カバーレイと補強板のオーバーラップ寸法を0.5mm以上としてください。
WHEN STIFFENER BOARD DIMENSION CAN NOT SECURE AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM.

REVISED EC NO: J2012-0121 DRAWN:YUASEGAWA 2011/07/25 CHKD:K TAKAHASHI 2011/07/25 APPR:KMORI KAWA 2011/07/28	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ++	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY DATE HONO 2009/07/21		TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY			
		10 OVER 30 UNDER	± 0.25	CHECKED BY DATE HSHIMOYAMA 2009/07/21					
		30 OVER	± 0.3	APPROVED BY DATE KMORI KAWA 2009/07/21		MOLEX MOLEX INCORPORATED			
		ANGULAR ±1 °		MATERIAL NO.					
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502598-001		2 OF 2		
	REV	C			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



注記)
NOTES

- 1.製品番号502598-**-11の詳細寸法は、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 502598-**-11 DETAIL DIMENSIONS,
SEE SALES DRAWING FOR CONNECTOR.
- 2.梱包数量:3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- 3.リードテープ長さ
LEAD TAPE LENGTH



- 4.カバートープの剥離強度については、IEC60286-3に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.
- 5.材料
MATERIAL
キャリアテープ:ポリスチレン(PS)
CARRIER TAPE:POLYSTYRENE(PS)
トップテープ:ポリエチレンテレフタレート(PET)、他
TOP TAPE :POLYETHYLENE TELEPHTHALATE(PET), OTHERS
リール:ポリスチレン(PS)
REEL:POLYSTYRENE(PS)
- 6.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

REVISED EC NO: J2011-0028 DRWN:HONO01 2010/07/06 CHKD:SHIMOYAMA 2009/07/21 APPR:KMORIKAWA 2010/07/08	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY HONO	DATE 2009/07/21	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (502598-**11 SERIES)			
		10 OVER 30 UNDER	± ---	CHECKED BY SHIMOYAMA	DATE 2009/07/21				
		30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2009/07/21				 MOLEX INCORPORATED
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.	SHEET NO.		
	B	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502598-002		1 OF 2
					SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

F

E

D

C

B

A

F

E

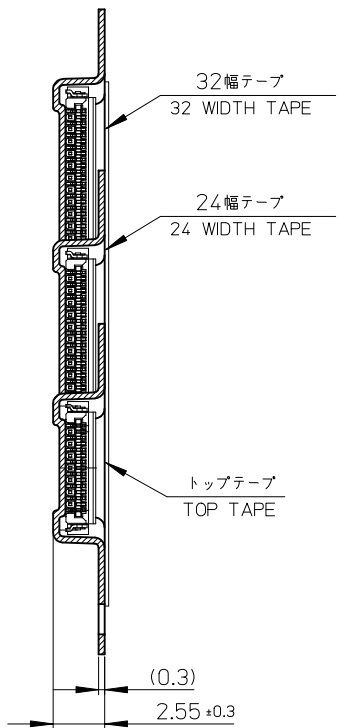
D

C

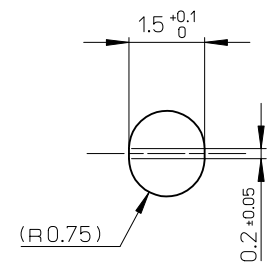
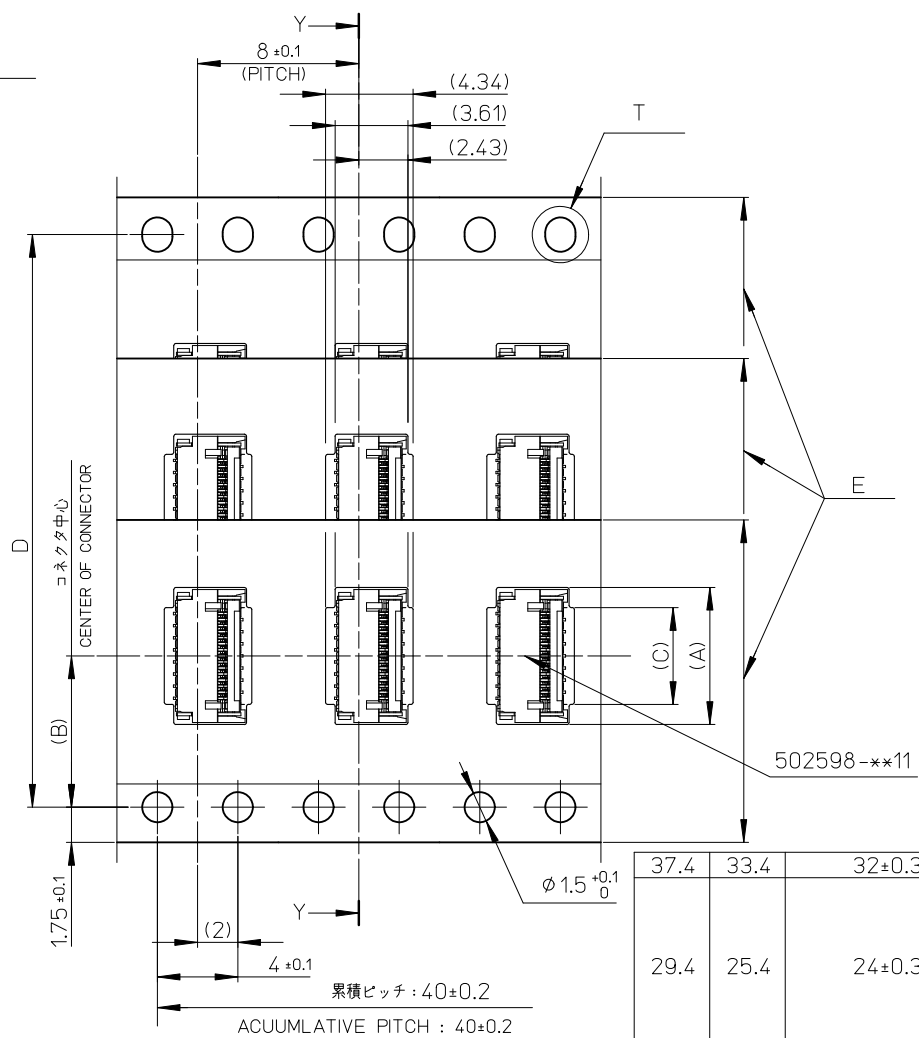
B

A

引き出し方向
PULL OUT DIRECTION



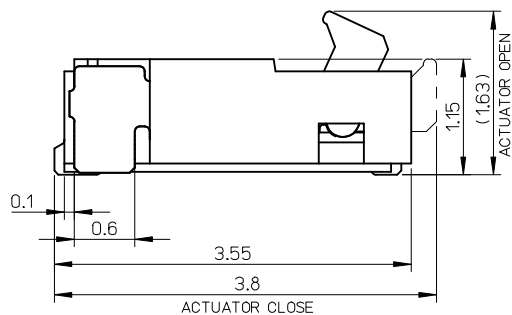
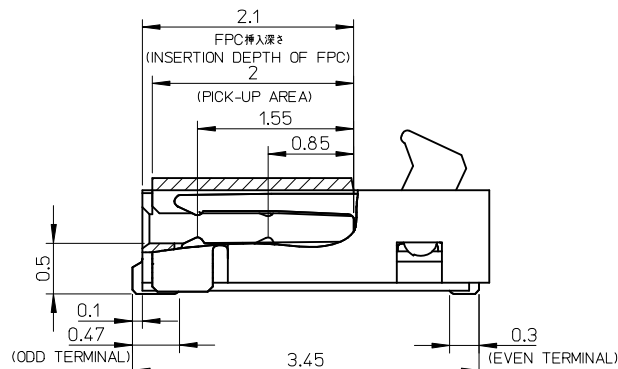
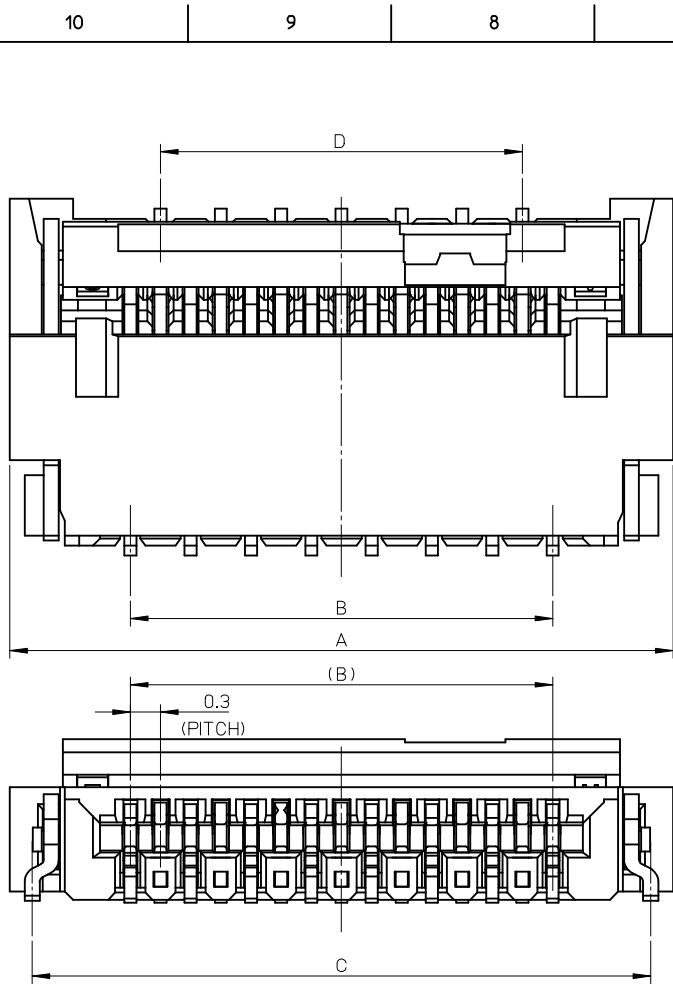
断面 Y-Y
SECTION Y-Y



T 部詳細
DETAIL T

37.4	33.4	32±0.3	28.4	15.7	14.2	17.6	502598-5191	51
29.4	25.4	24±0.3	±±	13.9	11.5	15.8	502598-4591	45
				12.1		14	502598-3991	39
				10.3		12.2	502598-3391	33
				9.1		11	502598-2991	29
				8.5		10.4	502598-2791	27
				7.9		9.8	502598-2591	25
				7.3		9.2	502598-2391	23
G	F	E キャリアテープ幅 EMBOSSED TAPE WIDTH	D	C	B	A	製 品 番 号 MATERIAL NO.	極 数 CIRCUITS

REVISED EC NO: J2011-0028 2010/07/06 DRWN:HON001 CHKD:SHIMOYAMA 2009/07/21 APPR:KMORIKAWA 2010/07/08	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY HONO	DATE 2009/07/21	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (502598-**11 SERIES)				
		10 OVER 30 UNDER	± ---	CHECKED BY SHIMOYAMA	DATE 2009/07/21					
		30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2009/07/21					
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.	SHEET NO.			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE							
	REV			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



注記 NOTES:

1.材質 MATERIAL

ハウジング: LCP(液晶ポリマー)、白色、ガラス充填、UL94V-0
HOUSING: LIQUID CRYSTAL POLYMER, WHITE (NATURAL)
GLASS FILLED, UL94V-0
アクチュエータ: ポリアミド樹脂
黒色、ガラス充填、UL94HB

ACTUATOR: POLYAMIDE
BLACK GLASS FILLED, UL94HB

ターミナル: 焼青銅 (t=0.12)
TERMINAL: PHOSPHOR BRONZE (t=0.12)

金具: 焼青銅 (t=0.15)
NAIL: PHOSPHOR BRONZE (t=0.15)

2.めっき仕様 PLATING

ターミナル TERMINAL

接点部: 金めっき 0.1μm以上
CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM

半田付け部: 金めっき
SOLDER TAIL AREA: GOLD

下地めっき: ニッケル 1.0μm以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM

金具 NAIL
錫めっき 1.0μm以上
TIN PLATING 1.0 MICROMETER MINIMUM

下地めっき: ニッケル 1.0μm以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM

3.平坦度は、0.1ミリ以下とする。
TAILS COPLANARITY TO BE 0.1 MAXIMUM.

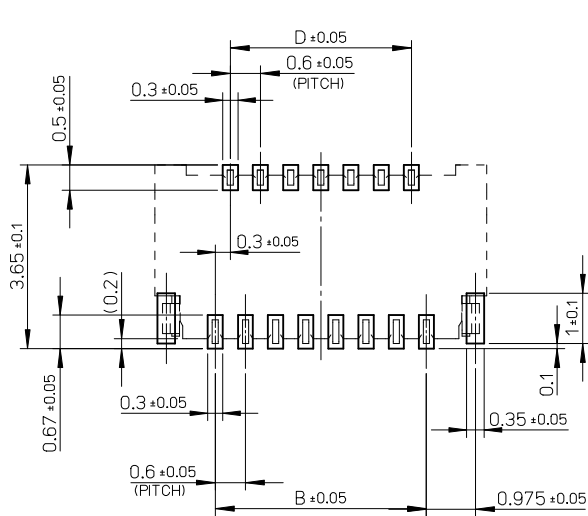
4.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

5.本製品は502598-**-91の端子材料変更品である。
THIS PRODUCT IS CHANGE OF TERMINAL MATERIAL
FOR 502598-**-91.

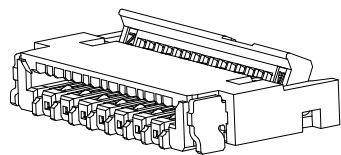
0.125	14.4	16.95	15	17.4	502598-5193	51
0.112	12.6	15.15	13.2	15.6	502598-4593	45
0.105	11.4	13.95	12.0	14.4	502598-4193	41
0.098	10.8	13.35	11.4	13.8	502598-3993	39
0.085	9	11.55	9.6	12	502598-3393	33
0.077	7.8	10.35	8.4	10.8	502598-2993	29
0.072	7.2	9.75	7.8	10.2	502598-2793	27
0.068	6.6	9.15	7.2	9.6	502598-2593	25
0.063	6	8.55	6.6	9	502598-2393	23
0.048	4.2	6.75	4.8	7.2	502598-1793	17
0.043	3.6	6.15	4.2	6.6	502598-1593	15
重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES NO. 502598-**-21

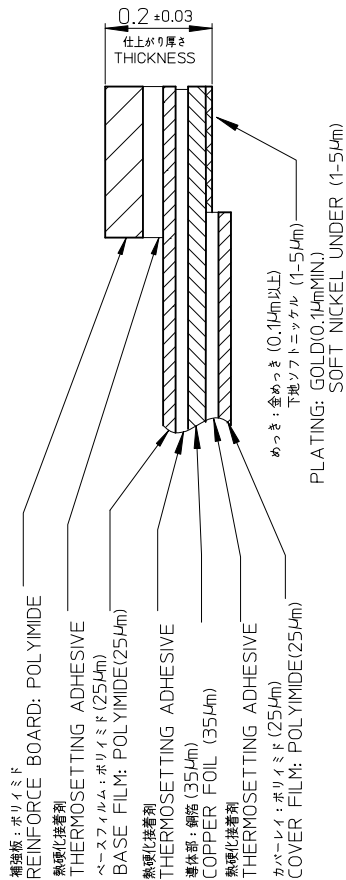
REVISED EC NO: J2014-0146 DRAWN: KAGUMO 2013/07/25 CHKD: TAKAHASHI 2013/08/30 APPR: YNOGAWA 2013/08/28	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	KMIYAHARA	2012/07/18	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY molex				
		10 OVER 30 UNDER	± 0.25	KTAKAHASHI	2012/07/18					
		30 OVER	± 0.3	KMORIKAWA	2012/08/01					
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502598-003		1 OF 2			
REV	B	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



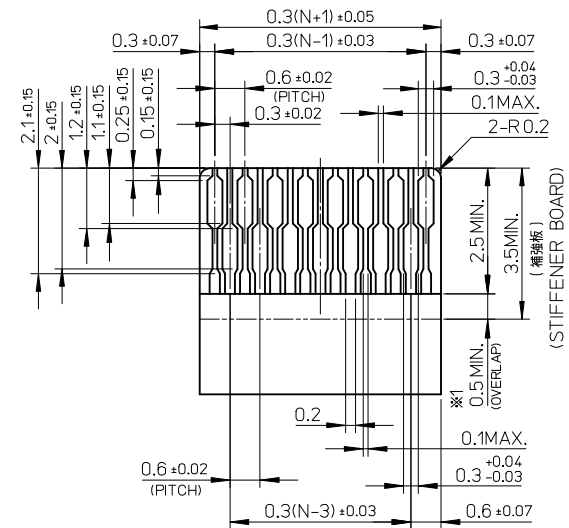
推奨基板寸法
RECOMMENDED P.W.B. PATTERN LAYOUT
マスク厚: 100 μm
マスク開口率: 100%
SCREEN THICKNESS: 100 μm
SCREEN OPEN RATIO: 100%



ISO VIEW (参考)



FPC構成推奨仕様
STRUCTURE OF FPC



適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

FPCについて:
抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON
ADHEREND BECAUSE THERE IS A POSSIBILITY THAT
THE EXTRA ADHESIVE CAUSES THE DEFECT IN
ELECTRICAL CONTINUITY.

REVISED	EC NO.: J2014-0146	2013/07/25	DRWN:KAGUMO	2013/08/30	CHKD:KAKAHASHI	2013/08/28	APPR:YNOGAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
									10 UNDER	± 0.2	DRAWN BY KMIYAHARA	DATE 2012/07/18	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY				
									10 OVER 30 UNDER	± 0.25	CHECKED BY KTAKAHASHI	DATE 2012/07/18					
									30 OVER	± 0.3	APPROVED BY KMORI KAWA		DATE 2012/08/01	molex			
									ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.				
REV	B								DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-502598-003		2 OF 2		
									SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



ООО «НИОКРсистемс» - это оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов. Реализуемая нашей компанией продукция насчитывает более полумиллиона наименований.

Благодаря этому наша компания предлагает к поставке практически не ограниченный ассортимент компонентов как оптовыми, мелкооптовыми партиями, так и в розницу.

Благодаря развитой сети поставщиков, помогаем в поиске и приобретении экзотичных или снятых с производства компонентов.

Наша компания это:

- Гарантия качества поставляемой продукции
- Широкий ассортимент
- Минимальные сроки поставок
- Техническая поддержка
- Подбор комплектации
- Индивидуальный подход
- Гибкое ценообразование
- Работаем по 275 ФЗ